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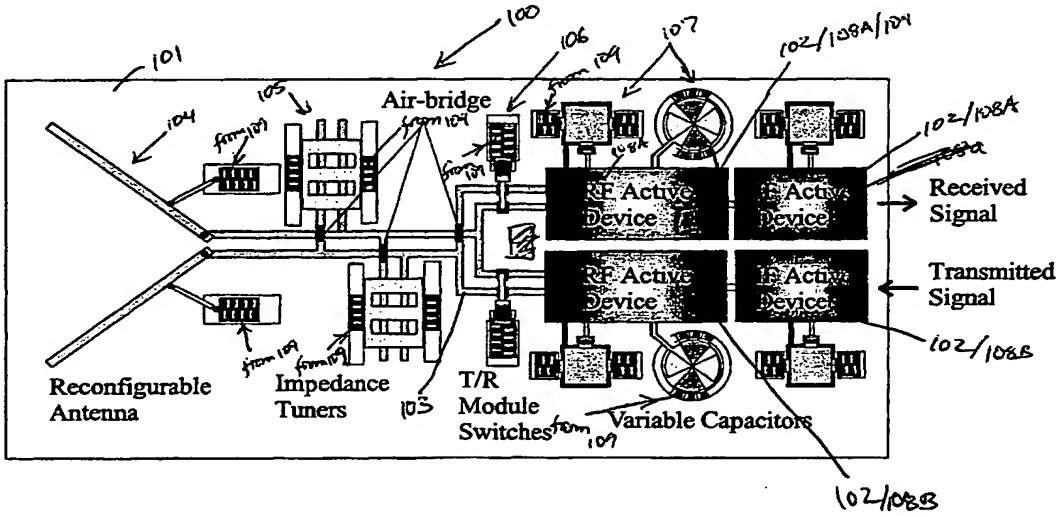
(54) Title: MEMS TRANSMISSION AND CIRCUIT COMPONENTS



(57) Abstract: An Rf device (100) that comprises unique MEMS RF transmission and circuit components (104-106) that are integrated together on a semiconductor chip (101) to form the RF device (100). These MEMS components (104-106) are monolithically formed on the chip (101) and are also reconfigurable on the chip (101).

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